

Piotr Mackowiak

List of Publications by Year in descending order

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11
papers

51
citations

1684188

5
h-index

1720034

7
g-index

11
all docs

11
docs citations

11
times ranked

44
citing authors

#	ARTICLE	IF	CITATIONS
1	Investigation and Modeling of Etching Through Silicon Carbide Vias (TSiCV) for SiC Interposer and Deep SiC Etching for Harsh Environment MEMS by DoE. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 437-445.	2.5	5
2	Development and Characterization of a Novel Low-Cost Water-Level and Water Quality Monitoring Sensor by Using Enhanced Screen Printing Technology with PEDOT:PSS. Micromachines, 2020, 11, 474.	2.9	9
3	Investigation of Etching SIC VIAS for High Power Electronics and Harsh Environment Mems. , 2020, , .		3
4	Fabrication of High Voltage Capable TSV Using Backside via Last Process and Laser Ablation of Dry Film BCB. , 2019, , .		4
5	A Novel Low Cost Wireless Incontinence Sensor System (Screen-Printed Flexible Sensor System) for Wireless Urine Detection in Incontinence Materials. Proceedings (mdpi), 2018, 2, .	0.2	6
6	Design and Application of a High-G Piezoresistive Acceleration Sensor for High-Impact Application. Micromachines, 2018, 9, 266.	2.9	11
7	Electrical Characterization of Low Temperature PECVD Oxides for TSV Applications. International Symposium on Microelectronics, 2018, 2018, 000728-000733.	0.0	5
8	A WSiâ€“WSiNâ€“Pt Metallization Scheme for Silicon Carbide-Based High Temperature Microsystems. Micromachines, 2016, 7, 193.	2.9	3
9	Development and fabrication of a very High-g sensor for very high impact applications. Journal of Physics: Conference Series, 2016, 757, 012016.	0.4	4
10	Evaluation and Signal Conditioning of Piezoresistive Silicon Pressure Sensor. Applied Mechanics and Materials, 2014, 530-531, 28-32.	0.2	1
11	Wireless Pressure Sensor System. Applied Mechanics and Materials, 2014, 530-531, 75-78.	0.2	0